



**NEWS RELEASE**  
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**SEC Upgrades the Model 860 Omni Bonder**

**Moorpark, Ca. – Semiconductor Equipment Corp.** has redesigned the Model 860 semiautomatic die bonder to make it easier to use, faster, more durable, and more versatile. The Omni Bonder has been the standard where a versatile die bonder is needed for low volume and development projects. Capabilities include flip chip, AuSn eutectic, epoxy transfer, ultrasonic bonding, and more. The latest version offers simple intuitive menus in a Windows XP operating system. The improved vision system features a 20:1 zoom lens, digital camera, image capture, and LED lighting. A new “Fast Head” increases throughput for flip chip and ultrasonic applications. Existing bond head and stage designs are still available. The Model 860 targets environments where versatility, ease of use, and low initial cost are important.

Semiconductor Equipment Corporation is recognized as the leading manufacturer and distributor of standard and customized die handling equipment and semiconductor dicing tape. Since 1975, SEC has installed thousands of production units worldwide for work in packaging and assembly operations including edge emitting lasers, flipchip, surface mount, and hi-reliability devices such as ball grid arrays, quad flat packs, and multi-chip modules.

(Photo enclosed – Upgraded SEC Model 860 Omni Bonder)